Device = VS1103B
Package = 48L LQFP 7x7x1.4 mm
REF DOC = BF49097 rev A (change Epoxy type)

Document: A
Rev: 3.0
Marking on device: **VS1103B**
PPPPPPPPPP
YYWW

where, PPPPPPPPPP = Lot ID
YYWW = assembly Year and Week > 1043

no	Part Name	Material Name	Component WT (mg)	Material Content (Element)	CAS#	Element Wt (%)	Element WT (mg)	WT% of total unit Wt	ppm
1	Die	Silicon Chip	13.226	Silicon	7440-21-3	100.00	13.226	7.185	71853.099
2	Lead Frame	Spot Ag Copper (Olin C7025)	79.408	Copper	7440-50-8	96.200	74.834	40.655	406551.747
				Ni	7440-02-0	3.000	2.334	1.268	12678.329
				Si	7440-21-3	0.650	0.506	0.275	2746.971
				Mg	7439-95-4	0.150	0.117	0.063	633.916
				Silver	7440-22-4		1.618	0.879	8790.134
3	Mold Compound	G700LX	86.394	Silica Fused	60676-86-0	81.500	70.411	38.252	382523.551
				Epoxy Resin	Trade Secret	10.000	8.639	4.694	46935.405
				Phenol Resin	Trade Secret	8.000	6.912	3.755	37548.324
				Carbon Black	1333-86-4	0.500	0.432	0.235	2346.770
4	Gold Wire	Gold (1.0 mils)	0.704	Au	7440-57-5	99.990	0.704	0.382	3824.249
				Dopant	-	0.010	0.000	0.000	0.382
5	Die Attach Material	CRM 1076 NS	1.438	Silver (Ag)	7440-22-4	82.000	1.179	0.641	6406.041
				Epoxy resin	9003-36-5	10.000	0.144	0.078	781.225
				Diluent	Trade Secret	2.000	0.029	0.016	156.245
				Dicyandiamide	461-58-5	0.900	0.013	0.007	70.310
				Hardener	Trade Secret	5.100	0.073	0.040	398.425
6	Solder	Sn 100	2.900	Sn	7440-31-5	99.987	2.900	1.575	15752.828
				Pb	7439-92-1	0.005	0.000	0.000	0.788
				Cu	7440-50-8	0.003	0.000	0.000	0.473
				Cd	7440-43-9	0.001	0.000	0.000	0.158
				Bi	7440-69-9	0.003	0.000	0.000	0.473
				Sb	7440-36-0	0.001	0.000	0.000	0.158
	Total Unit Weight =		184.070					100.000	